SCBS087C - FEBRUARY 1991 - REVISED JANUARY 1997

- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

The 'ABT16543 16-bit registered transceivers contain two sets of D-type latches for temporary storage of data flowing in either direction. The 'ABT16543 can be used as two 8-bit transceivers or one 16-bit transceiver. Separate latch-enable (LEAB or LEBA) and output-enable (OEAB or OEBA) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable (\overline{CEAB}) input must be <u>low to</u> enter data from A or to output data from B. If \overline{CEAB} is low and \overline{LEAB} is low, the A-to-B latches are transparent; a subsequent low-to-high transition of \overline{LEAB} puts the A latches in the storage mode. With \overline{CEAB} and \overline{OEAB} both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar but requires using the \overline{CEBA} , \overline{LEBA} , and \overline{OEBA} inputs.

SN54ABT16543 . . . WD PACKAGE SN74ABT16543 . . . DGG OR DL PACKAGE (TOP VIEW)



To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16543 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16543 is characterized for operation from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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SN54ABT16543, SN74ABT16543 16-BIT REGISTÉRED TRANSCEIVERS WITH 3-STATE OUTPUTS SCBS087C - FEBRUARY 1991 - REVISED JANUARY 1997

FUNCTION TABLE[†] (each 8-bit section)

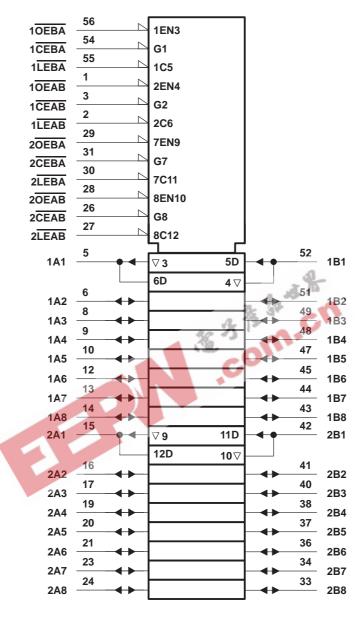
	OUTPUT			
CEAB	LEAB	OEAB	Α	В
Н	Χ	Х	Χ	Z
Х	Χ	Н	Χ	Z
L	Н	L	Χ	в ₀ ‡
L	L	L	L	L
L	L	L	Н	Н

[†] A-to-B data flow is shown; B-to-A flow control is the same except that it uses CEBA, LEBA, and OEBA.

[‡] Output level before the indicated steady-state input conditions were established



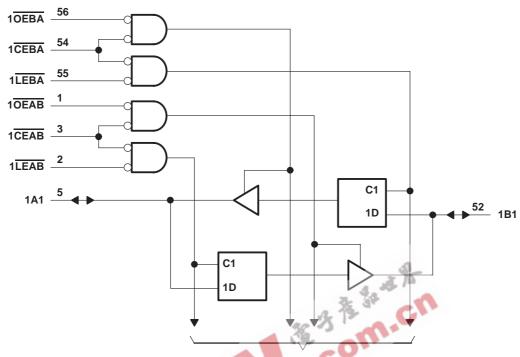
logic symbol†



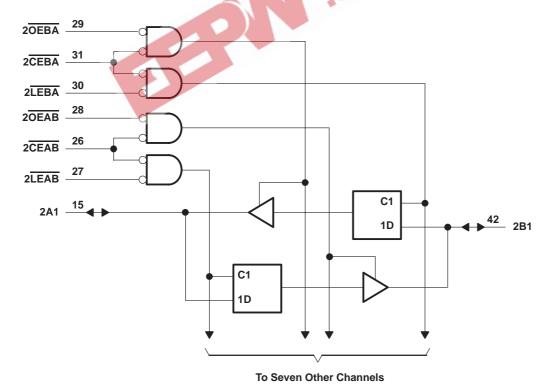
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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logic diagram (positive logic)



To Seven Other Channels



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state,	V _O –0.5 V to 5.5 V
Current into any output in the low state, Io: SN54ABT16543	96 mA
SN74ABT16543	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	
Package thermal impedance, θ _{JA} (see Note 2): DGG package	81°C/W
DL package	
Storage temperature range, T _{Sto}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

		4,35	SN54AB1	16543	SN74ABT	16543	UNIT
		76 GP	MIN	MAX	MIN	MAX	ONIT
VCC	Supply voltage	23	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	135	2		2		V
VIL	Low-level input voltage	C		0.8		0.8	V
VI	Input voltage		0	VCC	0	VCC	V
IOH	High-level output current			-24		-32	mA
l _{OL}	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
TA	Operating free-air temperature	_	– 55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		Т	A = 25°C	;	SN54ABT16543		SN74ABT16543		UNIT
PAR					TYP†	MAX	MIN	MAX	MIN	MAX	UNIT
VIK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	I _{OH} = -3 mA	2.5			2.5		2.5		
\/a		V _{CC} = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				V
		VCC = 4.5 V	I _{OH} = -32 mA	2*					2		
VOL		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V
VOL		VCC = 4.5 V	$I_{OL} = 64 \text{ mA}$			0.55*				0.55	V
V_{hys}	_				100						mV
l _I	Control inputs VCC = 5.5 V.		V _I = V _{CC} or GND			±1		±1		±1	μΑ
	A or B ports]				±100		±100		±100	,
I _{OZH} ‡		$V_{CC} = 5.5 \text{ V},$	V _O = 2.7 V			50**		10		50	μΑ
lozL [‡]		$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V			-50**	- 4	-10		-50	μΑ
I _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100	JG- /**			±100	μΑ
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high		w 3	50	C	50		50	μΑ
I _O §		$V_{CC} = 5.5 \text{ V},$	V _O = 2.5 V	-5 0	-100	-200	-50	-200	-50	-200	mA
		V _{CC} = 5.5 V,	Outputs high		C	2		2		2	
ICC	A or B ports	$I_{O} = 0$,	Outputs low			35		35		35	mA
		$V_I = V_{CC}$ or GND	Outputs disabled			2		2		2	
∆ICC¶		$V_{CC} = 5.5 \text{ V}$, One in Other inputs at V_{CC}				0.5		0.5		0.5	mA
C _i	Control inputs	V _I = 2.5 V or 0.5 V			3						pF
C _{io}	A or B ports	$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$			8.5						pF

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V _{CC} =	= 5 V, 25°C	SN54AB	Γ16543	SN74AB1	Г16543	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t _W	Pulse duration, LEAB or LEBA low		4		4		4		ns
	Octor Core data hafara IEARA an IERAA	High	1.5		1.5		1.5		ns
tsu	Setup time, data before LEAB↑ or LEBA↑	Low	3.5		3.5		3.5		
Ţ.,	Hold time, data after LEAB↑ or LEBA↑	High	1.5		1.5		1.5		
^t h	Low				2		2		ns



^{**} These limits apply only to the SN74ABT16543.

 $[\]dagger$ All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters IOZH and IOZL include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SN54ABT16543, SN74ABT16543 **16-BIT REGISTERED TRANSCEIVERS** WITH 3-STATE OUTPUTS SCBS087C - FEBRUARY 1991 - REVISED JANUARY 1997

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

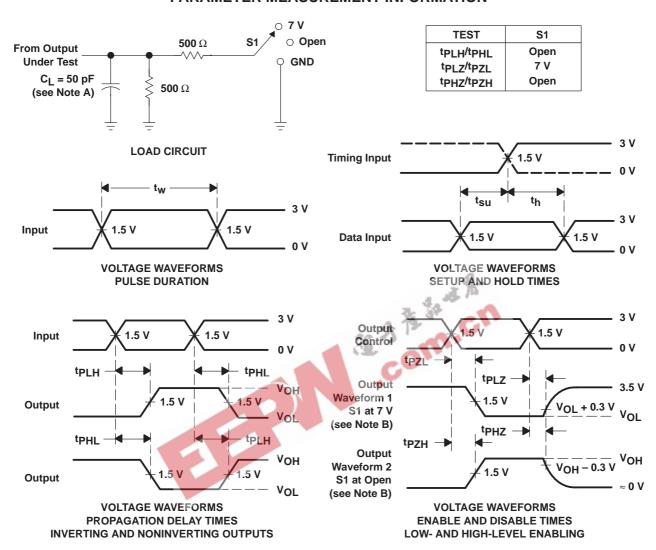
				SN5	4ABT16	543		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C	C = 5 V \ = 25°C	', ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
t _{PLH}	A or B	B or A	0.8	2.5	3.3	0.8	3.9	ns ns
t _{PHL}	AOIB	BULK	0.9	2.7	4.4	0.9	5.2	
t _{PLH}	Œ	A or B	1	3.1	4.3	1	5.3	
^t PHL	LE	AOID	1.2	3.3	4.8	1.2	5.7	
^t PZH	ŌĒ	A or B	0.8	3.4	4.3	0.8		ns
tPZL	OE .	AOID	1.1	3.8	7	1.1	7.9	113
^t PHZ	ŌĒ	A or B	1.9	4	6.3	1.9	7.2	ns
t _{PLZ}	OE .	AOID	1.6	3.3	4.6	1.6	5	115
^t PZH	CE	A or B	0.9	3.8	4.9	0.9	6.3	ns
tPZL	CE	AUID	1.2	4.2	6.8	1.2	7.9	115
^t PHZ	CE	A or B	2	4.5	6.4	2	7.3	ns
^t PLZ	1 CE	AUIB	1.7	3.9	5.1	1.7	5.6	115

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

				SN7	4ABT16	543		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V \ = 25°C	/, ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
t _{PLH}	A or B	B or A	1	2.5	3.3	1	3.8	ns
t _{PHL}	AULD	BULA	1	2.7	4.4	1	5.1	l lis
tPLH	LE	A or B	1	3.1	4.3	1	5.2	ns
t _{PHL}	LE	AOIB	1.2	3.3	4.8	1.2	5.6	
^t PZH	ŌĒ	A or B	1	3.4	4.3	1	5.2	ns
tPZL	OE	AOIB	1.1	3.8	5.9	1.1	7	113
t _{PHZ}	ŌĒ	A or B	1.9	4	5	1.9	5.7	ns
t _{PLZ}	OE	AOID	1.6	3.3	4.2	1.6	4.6	118
^t PZH	CE	A or B	1	3.8	4.9	1	6.2	ns
tPZL	CE	AUID	1.2	4.2	6.5	1.2	7.8	115
^t PHZ	CE	A or B	2	4.5	5.6	2	6.6	ns
^t PLZ	CE	7010	1.7	3.9	5.1	1.7	5.4	115

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50~\Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

26-Sep-2005

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9324101MXA	ACTIVE	CFP	WD	56	1	TBD	Call TI	Level-NC-NC-NC
74ABT16543DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16543DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16543DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16543DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16543DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16543DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ABT16543WD	ACTIVE	CFP	WD	56	1	TBD	Call TI	Level-NC-NC-NC

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): Ti's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

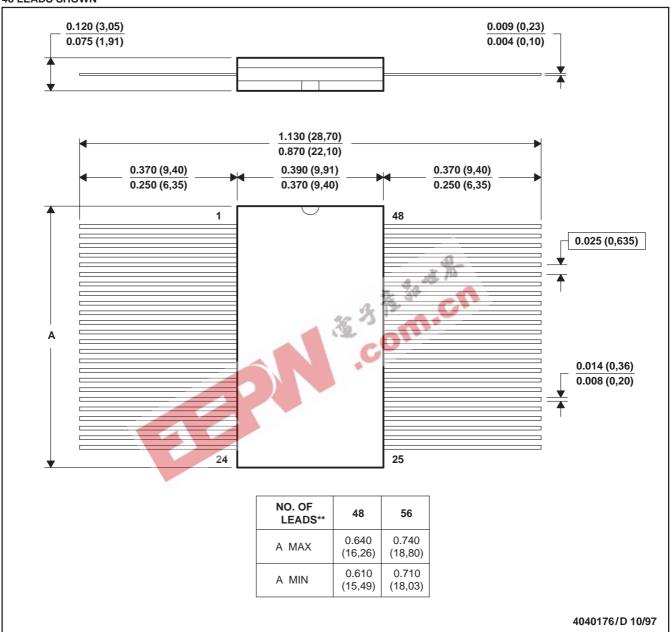
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WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

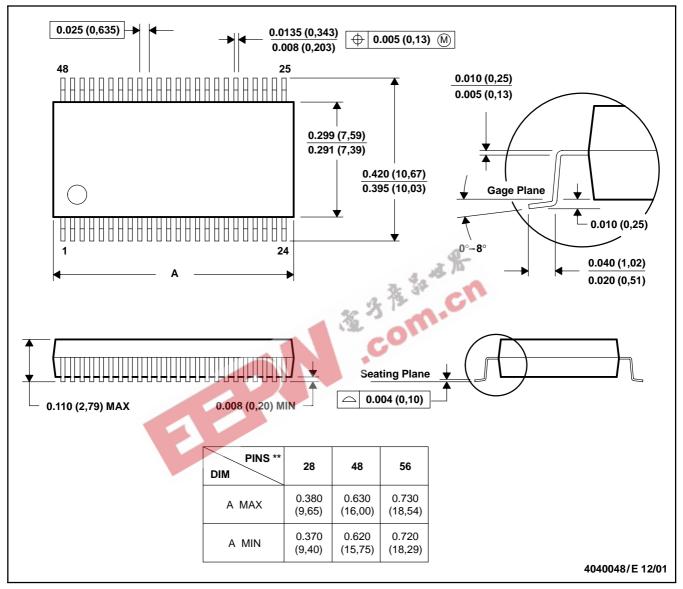
GDFP1-F56 and JEDEC MO-146AB



DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



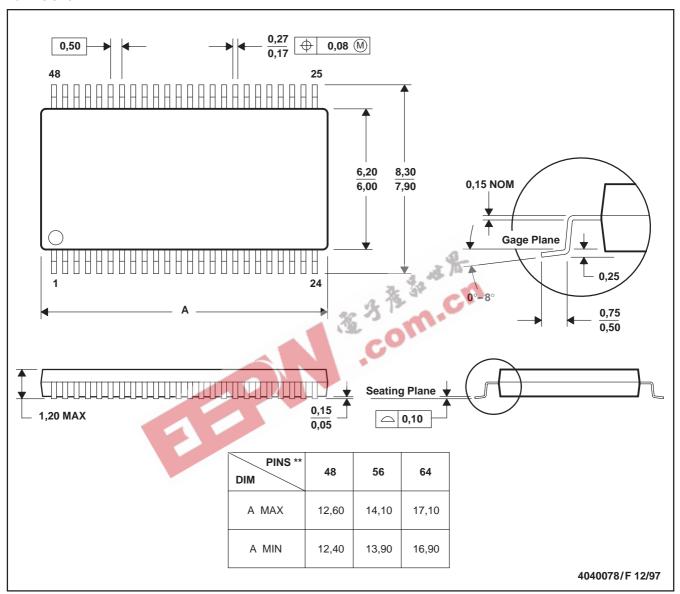
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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